Application No. 10/649,781 Amendment dated December 7, 2006

Reply to Office Action of September 12, 2006

AMENDMENTS TO THE ABSTRACT

Please amend the Abstract as below. A clean copy of the abstract is provided

as a separate attachment to this response.

The invention provides a method and apparatus for temporarily isolating a

die from other dies on a wafer commonly connected to one or more common

conductors. The conductors are connected to each die through a temporary isolation

device, such as a diode. The common conductor supplies a signal to all dice dies

during one set of test procedures, while the temporary isolation device can be used to

isolate a die from the common conductor during another set of test procedures.

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DSMDB-2145323v01

Docket No.: M4065.0468/P468-B